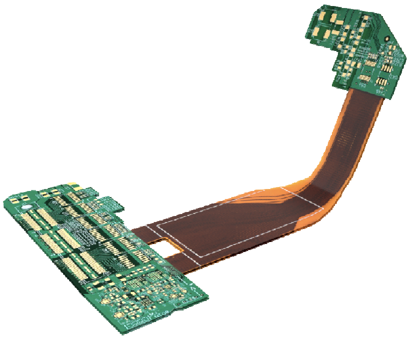
ESTEC

Make Success Our Responsibility

Rigid Flex Circuit Board

EXM-0012024

The Importance of Communication



Feature	Standard	Advanced
Number of Layers	1 - 16 Layers	26 Layers
Number of Flex Layers – Maximum	2 Layers	4 Layers
Base Material	FR-4, Polyimide (PI)	PET, BT，PTFE
Minimum Board Thickness	0.4mm	0.3mm
Minimum Board Size	50mm x 50mm	15mm x 15mm
Maximum Board Size	610mm x 460mm	1245mm x 730mm
Flexible Area Width – Minimum	5mm	2.5mm
Distance of Hole to Flexible Area	1.0mm minimum	0.5mm minimum
Distance of Conductor to Flexible Area	0.8mm minimum	0.4mm minimum
Surface Finishing	Electro-less Nickel Immersion Gold (ENIG) Electrolytic Nickel and Gold Immersion Tin Organic Solder-ability Preservative (OSP)	
Cover Material	Liquid Photo Imaging (LPI); Polyimide (PI)	
Profiling	Routing, Laser Cutting, Punching	